

MCP1252/3

Low-Noise, Positive-Regulated Charge Pump

Features

- · Inductorless, Buck/Boost, DC/DC Converter
- Low Power: 80 μA (typical)
- · High Output Voltage Accuracy:
 - ±2.5% (V_{OUT} fixed)
- · 120 mA Output Current
- · Wide Operating Temperature Range:
 - Industrial Temperature (I): -40°C to +85°C
 - Extended Temperature (E): -40°C to +125°C
- · Thermal Shutdown and Short-Circuit Protection
- · Uses Small Ceramic Capacitors
- · Switching Frequency:
 - MCP1252: 650 kHz
 - MCP1253: 1 MHz
- Low-Power Shutdown Mode: 0.1 μA (typical)
- Shutdown Input Compatible with 1.8V Logic
- V_{IN} Range: 2.0V to 5.5V
- Selectable Output Voltage (3.3V or 5.0V) or Adjustable Output Voltage
- · Space-Saving, 8-Lead MSOP
- · Soft Start Circuitry to Minimize Inrush Current
- AEC-Q100 Automotive Qualified, See Product Identification System

Applications

- · White LED Backlighting
- · Color Display Bias
- · Local 3V-to-5V Conversions
- · Flash Memory Supply Voltage
- · SIM Interface Supply for GSM Phones
- · Smart Card Readers
- PCMCIA Local 5V Supplies

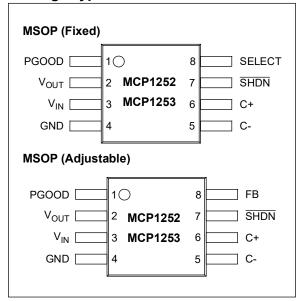
General Description

The MCP1252/3 are inductorless, positive-regulated charge pump DC/DC converters. The devices generate a regulated fixed (3.3V or 5.0V) or adjustable output voltage. The devices are specifically designed for applications requiring low noise and high efficiency and are able to deliver up to 120 mA output current. The devices allow the input voltage to be lower or higher than the output voltage by automatically switching between buck/boost operation.

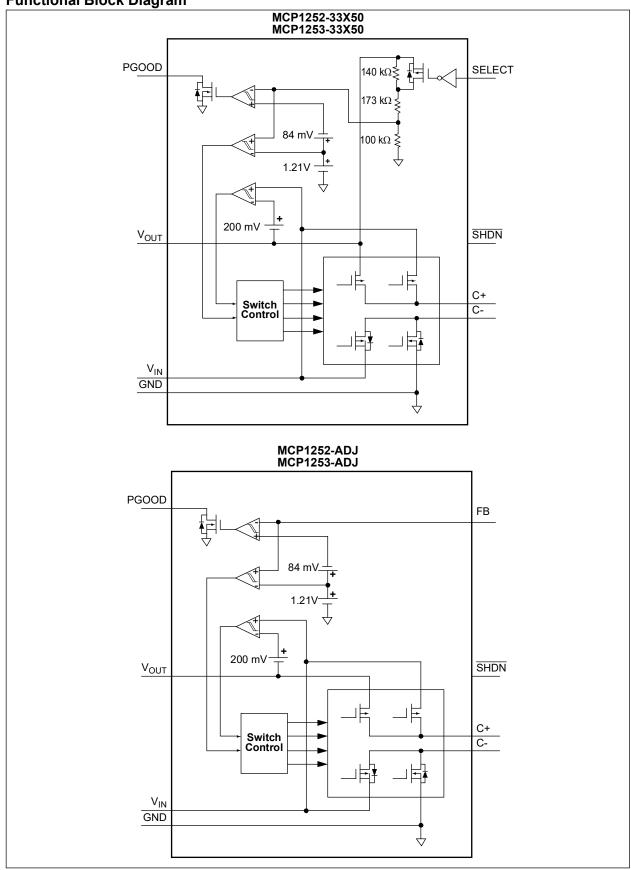
The MCP1252 has a switching frequency of 650 kHz, avoiding interference with sensitive IF bands. The MCP1253 has a switching frequency of 1 MHz and allows the use of smaller capacitors than the MCP1252, thus saving board space and cost.

Both devices feature a power-good output that can be used to detect out-of-regulation conditions. Extremely low supply current and low external parts count (three capacitors) make these devices ideal for small, battery-powered applications. A Shutdown mode is also provided for further power reduction. The MCP1252 and MCP1253 feature thermal and short-circuit protection and are offered in space-saving, 8-lead, MSOP packages.

Package Types



Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Power Supply Voltage, V _{IN}	6.0V
Voltage on Any Pin w.r.t. GND	0.3V to (V _{IN} + 0.3V)
Output Short Circuit Duration	continuous
Storage Temperature Range	-65°C to +150°C
Ambient Temperature with Power Applied	55°C to +125°C
Junction Temperature	+150°C
ESD Ratings ⁽¹⁾ :	
Human Body Model (1.5 k Ω in Series with 100 pF)	±400V
Charged Device Model	±1 kV

† Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Note 1: Testing was performed per AEC-Q100 Standards. ESD CDM was tested on the 6L SOT-23 package. For additional information, please contact your local Microchip sales office.

ELECTRICAL CHARACTERISTICS

Electrical Specifications: Unless otherwise specified, all limits are specified for $T_A = -40^{\circ}\text{C}$ to +85°C ("I" Temperature), $T_A = -40^{\circ}\text{C}$ to +125°C ("E" Temperature), $\overline{SHDN} = V_{IN}$, $C_{IN} = C_{OLIT} = 10 \,\mu\text{F}$, $C_{ELY} = 1 \,\mu\text{F}$, $I_{OLIT} = 10 \,\text{mA}$. Typical values are for $T_A = +25^{\circ}\text{C}$.

to +125°C ("E" Temperature), SHDN	$=$ V_{IN} , C_{IN} $=$	C _{OUT} = 10	μ F, $C_{FLY} = r$	1 μF, Ι _{ΟUT} =	10 mA. I	ypical values are for T _A = +25°C.
Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions
Selectable Output - MCP1252-33X	50, MCP1253	-33X50: SE	ELECT = VI	_N , V _{OUT} = 3	.3V	
Supply Voltage	V_{IN}	2.1	_	5.5	V	
Output Voltage Accuracy	V _{OUT}	-2.5	±0.5	+2.5	%	$2.3V \le V_{IN} \le 2.5V$, $I_{OUT} \le 80$ mA $2.5V \le V_{IN} \le 5.5V$, $I_{OUT} \le 120$ mA
Output Current	I _{OUT}	80	100	_	mA	$2.3V \le V_{IN} < 2.5V$
		120	150	_	mA	$2.5V \le V_{IN} \le 5.5V$
SELECT Logic Input Voltage High	V_{IH}	1.4	_	_	V	MCP1252-33X50, MCP1253-33X50
Selectable Output - MCP1252-33X	50, MCP1253	-33X50: SE	LECT = G	ND, V _{OUT} =	5.0V	
Supply Voltage	V_{IN}	2.7	_	5.5	V	
Output Voltage Accuracy	V _{OUT}	-2.5	±0.5	+2.5	%	$2.7V \le V_{IN} < 3.0V$, $I_{OUT} \le 40$ mA $3.0V \le V_{IN} \le 5.5V$, $I_{OUT} \le 120$ mA
Output Current	I _{OUT}	40	80	_	mA	2.7V ≤ V _{IN} < 3.0V
		120	150	_		$3.0V \le V_{IN} \le 5.5V$
SELECT Logic Input Voltage Low	V _{IL}	_	_	0.4	V	MCP1252-33X50, MCP1253-33X50
Adjustable Output - MCP1252-AD	, MCP1253-A	ADJ				
Supply Voltage	V _{IN}	2.0	_	5.5	V	
Output Voltage Adjustment Range	V _{OUT}	1.5	_	5.5	V	V _{OUT(MAX)} < 2 x V _{IN}
FB Regulation Voltage	V_{FB}	1.18	1.21	1.24	V	MCP1252-ADJ, MCP1253-ADJ
ALL DEVICES						
Supply Current	I _{DD}	_	60	120	μΑ	No load
Output Short-Circuit Current	I _{sc}	_	200	_	mA	V _{OUT} = GND, foldback current
Shutdown Current	I _{SHDN}	_	0.1	2.0	μΑ	SHDN = 0V
Power Efficiency	η	_	81	_	%	$V_{IN} = 3.0V, V_{OUT} = 5V$ $I_{OUT} = 120 \text{ mA}$
			68	_		V _{IN} = 3.6V, V _{OUT} = 5V I _{OUT} = 120 mA
SHDN Logic Input Voltage Low	V_{IL}	_	_	0.4	V	

ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise specified, all limits are specified for $T_A = -40^{\circ}\text{C}$ to +85°C ("I" Temperature), $T_A = -40^{\circ}\text{C}$ to +125°C ("E" Temperature), $\overline{SHDN} = V_{IN}$, $C_{IN} = C_{OUT} = 10~\mu\text{F}$, $C_{FLY} = 1~\mu\text{F}$, $I_{OUT} = 10~\text{mA}$. Typical values are for $T_A = +25^{\circ}\text{C}$.

Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions
SHDN Logic Input Voltage High	V _{IH}	1.4	_	_	V	
PGOOD Output Voltage	P _{GOOD_VOL}	_	0.01	_	٧	I _{PGOOD} = 0.5 mA
PGOOD Threshold Voltage	V_{TH}	_	0.93V _{OUT}	_	V	
PGOOD Hysteresis	V _{HYS}	_	0.04V _{OUT}	_	V	

AC CHARACTERISTICS

Electrical Specifications: Unless otherwise specified, all limits are specified for $T_A = -40^{\circ}C$ to $+85^{\circ}C$ ("I" Temperature), $T_A = -40^{\circ}C$ to $+125^{\circ}C$ ("E" Temperature), $\overline{SHDN} = V_{IN}$, $C_{IN} = C_{OUT} = 10 \,\mu\text{F}$, $C_{FLY} = 1 \,\mu\text{F}$, $I_{OUT} = 10 \,\text{mA}$. Typical values are for $T_A = +25^{\circ}C$.

Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions
Internal Oscillator Frequency	Fosc	520	650	780	kHz	MCP1252
		800	1000	1200		MCP1253
Ripple Voltage	V_{RIP}	_	50	_	mV _{p-p}	MCP1252
		_	45	_	mV _{p-p}	MCP1253
V _{OUT} Wake-Up Time From Shutdown	T _{WKUP}				µsec	$\begin{aligned} & \frac{\text{V}_{\text{IN}} = 3.6\text{V, I}_{\text{OUT}} = 10 \text{ mA,}}{\text{SHDN}} = & \text{V}_{\text{IH}(\text{MIN})}, \\ & \text{V}_{\text{OUT}} \text{ from 0 to 90\% Nominal} \\ & \text{Regulated Output Voltage} \end{aligned}$
		_	200	_		SELECT = V _{IN}
		_	300	_		SELECT = GND

TEMPERATURE SPECIFICATIONS

Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions
Temperature Ranges:						
Specified Temperature Range	T _A	-40	_	+85	°C	"I" Temperature range
		-40	_	+125		"E" Temperature range
Maximum Operating Junction Temperature	T _J	_	_	+125	°C	
Storage Temperature Range	T _A	-65	_	+150	°C	
Thermal Package Resistances:						
Thermal Resistance, 8 Pin MSOP	$\theta_{\sf JA}$	_	206	_	°C/W	Single-Layer SEMI G42-88 board, Natural Convection

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, V_{IN} = 3.6V, T_A = 25°C, C_{IN} = C_{OUT} = 10 μ F, C_{FLY} = 1 μ F, all capacitors X7R ceramic.

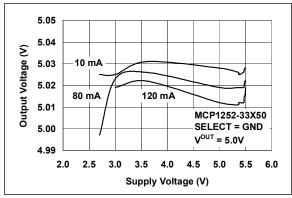


FIGURE 2-1: Output Voltage vs. Supply Voltage (MCP1252-33X50).

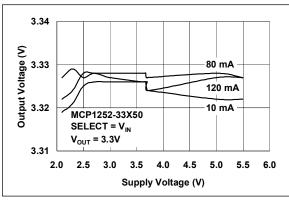


FIGURE 2-2: Output Voltage vs. Supply Voltage (MCP1252-33X50).

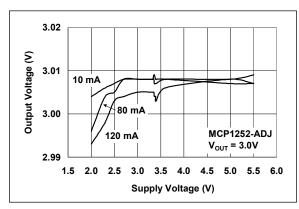


FIGURE 2-3: Output Voltage vs. Supply Voltage (MCP1252-ADJ).

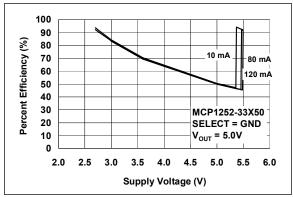


FIGURE 2-4: Percent Efficiency vs. Supply Voltage (MCP1252-33X50).

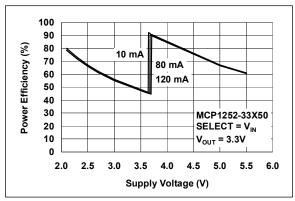


FIGURE 2-5: Power Efficiency vs. Supply Voltage (MCP1252-33X50).

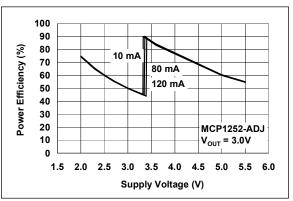


FIGURE 2-6: Power Efficiency vs. Supply Voltage (MCP1252-ADJ).

Note: Unless otherwise indicated, V_{IN} = 3.6V, T_A = 25°C, C_{IN} = C_{OUT} = 10 μ F, C_{FLY} = 1 μ F, all capacitors X7R ceramic.

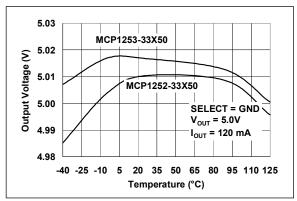


FIGURE 2-7: Output Voltage vs. Temperature (MCP1252-33X50, MCP1253-33X50).

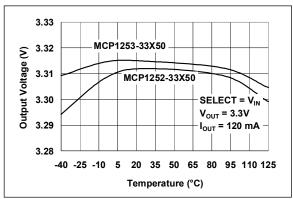


FIGURE 2-8: Output Voltage vs. Temperature (MCP1252-33X50, MCP1253-33X50).

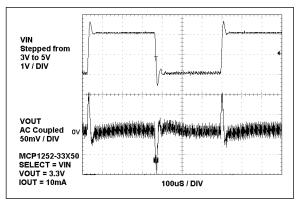


FIGURE 2-9: Line Transient Response.

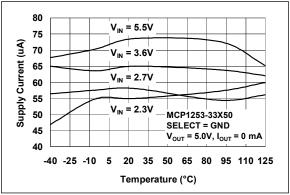


FIGURE 2-10: Quiescent Current vs. Temperature (MCP1253-33X50).

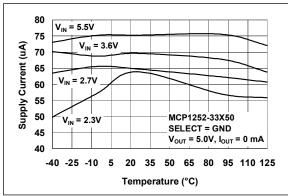


FIGURE 2-11: Quiescent Current vs. Temperature (MCP1252-33X50).

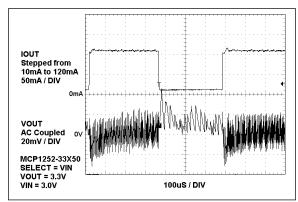


FIGURE 2-12: Load Transient Response.

Note: Unless otherwise indicated, V_{IN} = 3.6V, T_A = 25°C, C_{IN} = C_{OUT} = 10 μ F, C_{FLY} = 1 μ F, all capacitors X7R ceramic.

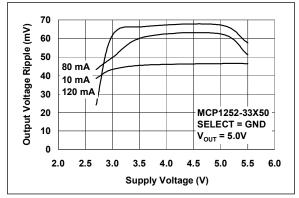


FIGURE 2-13: Output Voltage Ripple vs. Supply Voltage (MCP1252-33X50).

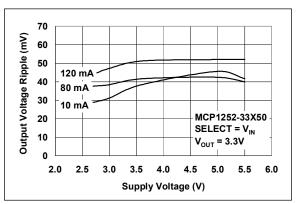


FIGURE 2-14: Output Voltage Ripple vs. Supply Voltage (MCP1252-33X50).

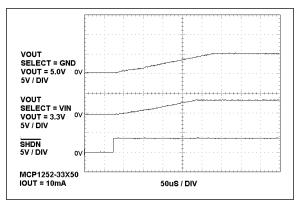


FIGURE 2-15: Start-Up (MCP1252-33X50).

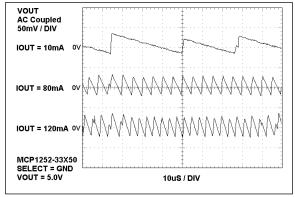


FIGURE 2-16: Output Voltage Ripple vs. Time.

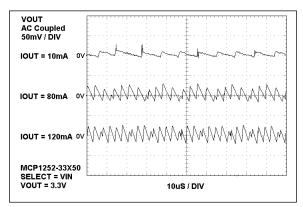


FIGURE 2-17: Output Voltage Ripple vs. Time.

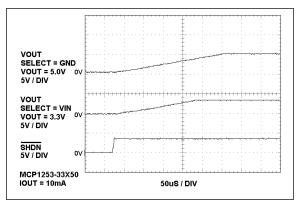


FIGURE 2-18: Start-Up (MCP1253-33X50).

3.0 PIN DESCRIPTION

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin Number	Name	Function
1	PGOOD	Open-Drain Power GOOD Output
2	V _{OUT}	Regulated Output Voltage
3	V _{IN}	Power Supply Input
4	GND	Ground Terminal
5	C-	Flying Capacitor Negative Terminal
6	C+	Flying Capacitor Positive Terminal
7	SHDN	Shutdown Mode, Active-Low Input
8	SELECT	Output Voltage Select Pin (MCP1252-33X50, MCP1253-33X50)
	FB	Feedback Input Pin for Adjustable Output (MCP1252-ADJ, MCP1253-ADJ)

3.1 Open-Drain Power Good Output (PGOOD)

PGOOD is a high-impedance when the output voltage is in regulation. A logic low is asserted when the output falls 7% (typical) below the nominal value. The PGOOD output remains low until V_{OUT} is within 3% (typical) of its nominal value. On start-up, this pin indicates when the output voltage reaches its final value. PGOOD is high-impedance when \overline{SHDN} is low.

3.2 Regulated Output Voltage (V_{OUT})

Bypass to GND with a filter capacitor.

3.3 Power Supply Input (V_{IN})

It is recommended that $V_{\mbox{\scriptsize IN}}$ be tied to a ceramic bypass capacitor.

3.4 Ground (GND)

It is recommended that the ground pin be tied to a ground plane for best performance.

3.5 Flying Capacitor Negative Terminal (C-)

The charge pump capacitor (flying capacitor) is used to transfer charge from the input supply to the regulated output.

It is recommended that a low-ESR (equivalent series resistance) capacitor be used.

3.6 Flying Capacitor Positive Terminal (C+)

The charge pump capacitor (flying capacitor) is used to transfer charge from the input supply to the regulated output.

Proper orientation is imperative when using a polarized capacitor.

3.7 Shutdown Input (SHDN)

A logic low signal applied to SHDN disables the device. A logic high signal applied to this pin allows normal operation.

3.8 Select (SELECT) Input or Feedback (FB) Input

MCP1252-33X50, MCP1253-33X50:

SELECT: Select Input Pin.

Connect SELECT to $V_{\rm IN}$ for 3.3V fixed output. Connect SELECT to GND for a 5.0V fixed output.

MCP1252-ADJ. MCP1253-ADJ:

FB: Feedback Pin.

A resistor divider connected to this pin determines the adjustable V_{OUT} value (1.5V to 5.5V).

4.0 DEVICE OVERVIEW

4.1 Theory of Operation

The MCP1252 and MCP1253 family of devices employ a switched capacitor charge pump to buck or boost an input supply voltage (V_{IN}) to a regulated output voltage. Referring to the Functional Block Diagram and Figure 4-1, the devices perform conversion and regulation in three phases. When the devices are not in Shutdown mode and a steady-state condition has been reached, the three phases are continuously cycled through. The first phase transfers charge from the input to the flying capacitor (C_{FLY}) connected to pins C+ and C-. This phase always occurs for half of the internal oscillator period. During this phase, switches S_1 and S_2 are closed.

Once the first phase is complete, all switches are opened and the second phase (Idle phase) is entered. The device compares the internal or external feedback voltage with an internal reference. If the feedback voltage is below the regulation point, the device transitions to the third phase.

The third phase transfers energy from the flying capacitor to the output capacitor connected to V_{OUT} and the load. If regulation is maintained, the device returns to the Idle phase. If the charge transfer occurs for half the internal oscillator period, more charge is needed in the flying capacitor and the device transitions back to the first phase.

The regulation control is hysteretic, otherwise referred to as a bang-bang control. The output is regulated around a fixed reference with some hysteresis. As a result, typically 50 mV of peak-to-peak ripple will be observed at the output independent of load current. The frequency of the output ripple, however, will be influenced heavily by the load current and output capacitance. The maximum frequency that will be observed is equal to the internal oscillator frequency.

The devices automatically transition between buck or boost operation. This provides a low-cost, compact and simple solution for step-down/step-up DC/DC conversion. This is especially true for battery-operated applications that require a fixed output above or below the input.

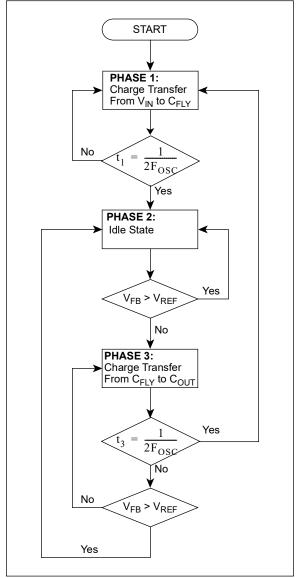


FIGURE 4-1: Flow Algorithm.

4.2 Power Efficiency

The power efficiency, η , is determined by the mode of operation. In Boost mode, the efficiency is approximately half of a linear regulator. In Buck mode, the efficiency is approximately equal to that of a linear regulator. Equation 4-1 shows the formulas that can be used to approximate the power efficiency with any significant amount of output current. At light loads, the quiescent current of the device must be taken into consideration.

EQUATION 4-1:

$$\eta_{BOOST} = \frac{P_{OUT}}{P_{IN}} = \frac{V_{OUT} \times I_{OUT}}{V_{IN} \times 2 \times I_{OUT}} = \frac{V_{OUT}}{V_{IN} \times 2}$$

$$\eta_{BUCK} = \frac{P_{OUT}}{P_{IN}} = \frac{V_{OUT} \times I_{OUT}}{V_{IN} \times I_{OUT}} = \frac{V_{OUT}}{V_{IN}}$$

4.3 Shutdown Mode

Driving \overline{SHDN} low places the MCP1252 or MCP1253 in a low-power Shutdown mode. This disables the charge pump switches, oscillator and control logic, reducing the quiescent current to 0.1 μ A (typical). The PGOOD output is in a high-impedance state during shutdown.

4.4 PGOOD Output

The PGOOD output is an open-drain output that sinks current when the regulator output voltage falls below $0.93 V_{OUT}$ (typical). The output voltage can either be fixed when the selectable output device is chosen (MCP1252-33X50, MCP1253-33X50) or adjustable from an external resistive divider when the adjustable device is chosen (MCP1252-ADJ, MCP1253-ADJ). If the regulator output voltage falls below $0.93 V_{OUT}$ (typical) for less than 200 µsec and then recovers, glitch-immunity circuits prevent the PGOOD signal from transitioning low. A 10 k Ω to 1 M Ω pull-up resistor from PGOOD to V_{OUT} may be used to provide a logic output. Connect PGOOD to GND or leave unconnected if not used.

4.5 Soft Start and Short-Circuit Protection

The MCP1252 and MCP1253 feature foldback short-circuit protection. This circuitry provides an internal soft start function by limiting inrush current during start-up and also limits the output current to 200 mA (typical) if the output is shorted to GND. The internal soft start circuitry requires approximately 300 μ sec, typical with a 5V output, from either initial power-up or release from shutdown for the output voltage to be in regulation.

4.6 Thermal Shutdown

The MCP1252 and MCP1253 feature thermal shutdown with temperature hysteresis. When the die temperature exceeds 160°C, typically, the device shuts down. When the die cools by 15°C, typically, the device automatically turns back on. If high die temperature is caused by output overload and the load is not removed, the device will turn on and off, resulting in a pulse output.

5.0 APPLICATIONS

The MCP1252 and MCP1253 are inductorless, positive-regulated, charge pump DC/DC converters. A typical circuit configuration for the fixed output version is depicted in Figure 5-1. The adjustable version is depicted in Figure 5-2.

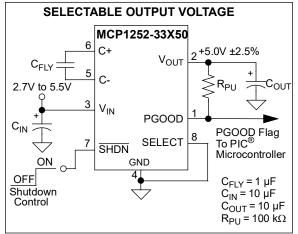


FIGURE 5-1: Typical Circuit Configuration for Fixed Output Device.

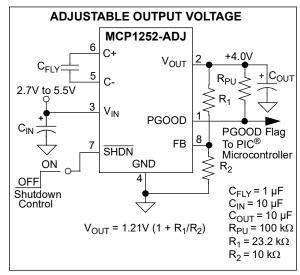


FIGURE 5-2: Typical Circuit Configuration for Adjustable Output Device.

5.1 Capacitor Selection

The style and value of capacitors used with the MCP1252 and MCP1253 family of devices determine several important parameters such as output voltage ripple and charge pump strength. To minimize noise and ripple, it is recommended to use low-ESR $(0.1\,\Omega)$ capacitors for both C_{IN} and $C_{OUT}.$ These capacitors should be either ceramic or tantalum and should be 10 μF or higher. Aluminum capacitors are not recommended because of their high ESR.

If the source impedance to V_{IN} is very low, up to several megahertz, C_{IN} may not be required. Alternatively, a smaller value of C_{IN} may be substituted for the recommended 10 μ F, but will not be as effective in preventing ripple on the V_{IN} pin.

The value of C_{OUT} controls the amount of output voltage ripple present on V_{OUT} . Increasing the size of C_{OUT} will reduce output ripple at the expense of a slower turn-on time from shutdown and a higher inrush current.

The flying capacitor (C_{FLY}) controls the strength of the charge pump. In order to achieve the maximum rated output current (120 mA), it is necessary to have at least 1 μF of capacitance for the flying capacitor. A smaller flying capacitor delivers less charge per clock cycle to the output capacitor, resulting in lower output ripple. The output ripple is reduced at the expense of maximum output current and efficiency.

5.2 Output Voltage Setting

The MCP1252-33X50 and MCP1253-33X50 feedback controllers select between an internally set, regulated output voltage (3.3V or 5.0V). Connect SELECT to GND for a regulated 5.0V output and connect SELECT to V_{IN} for a regulated 3.3V output.

The MCP1252-ADJ and MCP1253-ADJ utilize an external resistor divider that allows the output voltage to be adjusted between 1.5V and 5.5V. For an adjustable output, connect a resistor between V_{OUT} and FB (R_1) and another resistor between FB and GND $(R_2).$ In the following equation, choose R_2 to be less than or equal to 30 $k\Omega$ and calculate R_1 as follows:

EQUATION 5-1:

$$R_1 = R_2[(V_{OUT}/V_{FB}) - 1]$$

Using R_1 value obtained by Equation 5-1, we can calculate V_{OUT} using the following Equation 5-2:

EQUATION 5-2:

$$V_{OUT} = V_{FB}(1 + R_1/R_2)$$

Where:

V_{OUT} is the desired output voltage from 1.5V to 5.5V

 V_{FB} is the internal regulation voltage, nominally 1.21V

Note that the tolerance of the external resistors will have an effect on the accuracy of the output voltage. For optimum results, it is recommended that the external resistors have a tolerance no larger than 1%.

5.3 Recommended Layout

The MCP1252 and MCP1253 family of devices transfer charge at high switching frequencies, producing fast, high-peak, transient currents. As a result, any stray inductance in the component layout will produce unwanted noise in the system. Proper board layout techniques are required to ensure optimum performance. Figure 5-3 depicts the recommended board layout. The input capacitor connected between V_{IN} and GND and the output capacitor connected between V_{OUT} and GND are 10 μF ceramic, X7R dielectric in 1206 packages. The flying capacitor connected between C+ and C- is a 1 μF ceramic, X7R dielectric in a 0805 package. The layout is scaled 3:1.

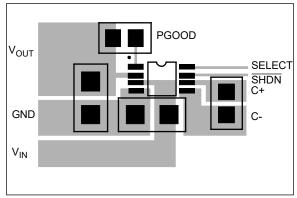
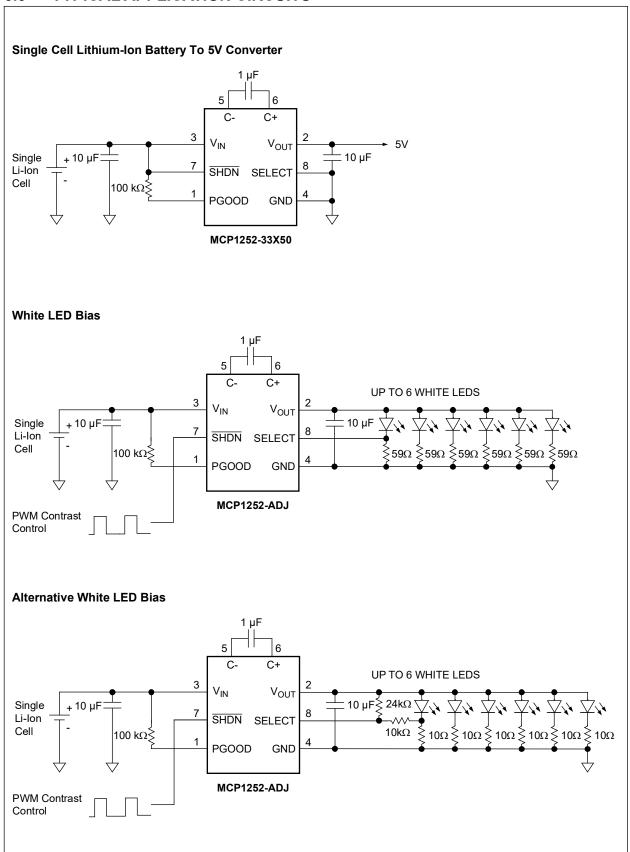


FIGURE 5-3: Recommended Printed Circuit Board Layout.

6.0 TYPICAL APPLICATION CIRCUITS



7.0 PACKAGING INFORMATION

7.1 **Package Marking Information**

8-Lead MSOP (Fixed)



Example:



8-Lead MSOP (Adjustable)



Example:



OR



Legend: XX...X Customer-specific information

Year code (last digit of calendar year) ΥY Year code (last 2 digits of calendar year) WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code (e3)

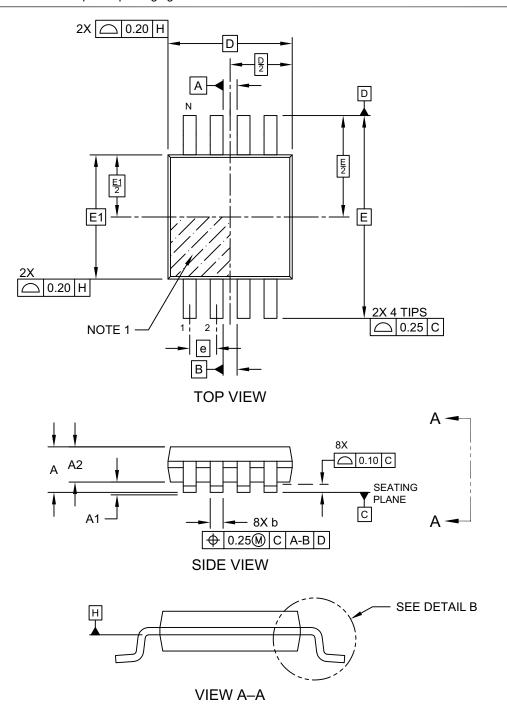
Pb-free JEDEC® designator for Matte Tin (Sn)

This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

In the event the full Microchip part number cannot be marked on one line, it will Note: be carried over to the next line, thus limiting the number of available characters for customer-specific information.

8-Lead Plastic Micro Small Outline Package (UA) - 3x3 mm Body [MSOP]

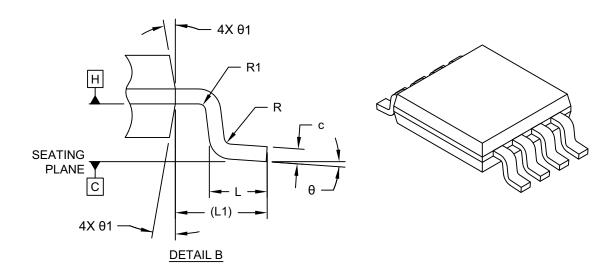
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-111-UA Rev F Sheet 1 of 2

8-Lead Plastic Micro Small Outline Package (UA) - 3x3 mm Body [MSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	N	MILLIMETER	S
	Dimension Limits	MIN	NOM	MAX
Number of Terminals	N		8	
Pitch	е		0.65 BSC	
Overall Height	А	_	_	1.10
Standoff	A1	0.00	_	0.15
Molded Package Thickness	A2	0.75	0.85	0.95
Overall Length	D		3.00 BSC	
Overall Width	E	4.90 BSC		
Molded Package Width	E1	3.00 BSC		
Terminal Width	b	0.22	_	0.40
Terminal Thickness	С	0.08	_	0.23
Terminal Length	L	0.40	0.60	0.80
Footprint	L1		0.95 REF	
Lead Bend Radius	R	0.07	_	_
Lead Bend Radius	R1	0.07	_	_
Foot Angle	θ	0°	_	8°
Mold Draft Angle	θ1	5°	_	15°

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- 3. Dimensioning and tolerancing per ASME Y14.5M

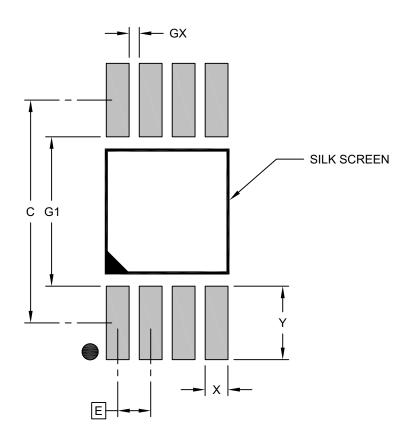
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-111-UA Rev F Sheet 2 of 2

8-Lead Plastic Micro Small Outline Package (UA) - 3x3 mm Body [MSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	N	<i>I</i> ILLIMETER	S	
Dimension	MIN	NOM	MAX	
Contact Pitch E			0.65 BSC	
Contact Pad Spacing	С		4.40	
Contact Pad Width (X8)	Х			0.45
Contact Pad Length (X8)	Υ			1.45
Contact Pad to Contact Pad (X4)	G1	2.95		
Contact Pad to Contact Pad (X6)	GX	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

 ${\tt BSC: Basic \ Dimension. \ Theoretically \ exact \ value \ shown \ without \ tolerances.}$

Microchip Technology Drawing C04-2111-UA Rev F

APPENDIX A: REVISION HISTORY

Revision D (August 2023)

- Added automotive qualification to Features and examples to Product Identification System.
- Updated Absolute Maximum Ratings† to better describe the part.
- Updated Section 7.0, Packaging Information.
- Made minor text and format changes throughout the document.

Revision C (July 2014)

• Added the Extended Temperature (E) option and related information throughout the document.

Revision B (January 2013)

· Added a note to each package outline drawing.

Revision A (November 2002)

· Original release of this document.

M	CP'	1252	/3
	VI.		1

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X] ⁽¹⁾	-XXX	X	<u>/XX</u>	xxx
Device	Tape and Reel Option	Voltage Option	Temp. Range	Package	Qualification

MCP1252: Low-Noise, Positive-Regulated Charge Pump MCP1252T: Low-Noise, Positive-Regulated Charge Pump

(Tape and Reel)

MCP1253: Low-Noise, Positive-Regulated Charge Pump MCP1253T: Low-Noise, Positive-Regulated Charge Pump

(Tape and Reel)

= Tape and Reel⁽¹⁾ Tape and Reel Option: T

Output Voltage: = Adjustable Voltage 33X50 = Selectable Voltage

= -40°C to +85°C Temperature Range: (Industrial)

= -40°C to +125°C (Extended) (MCP1253 only) Ε

Package: MS = Plastic Micro Small Outline (MSOP), 8-Lead

Qualification*: Blank = Standard Part

= AEC-Q100 Automotive Qualified

*Currently available VAO variants are:

MCP1253-ADJI/MSVAO. MCP1253T-ADJI/MSVAO, MCP1253T-33X50I/MSVAO, MCP1253T-33X50E/MSVAO Examples for MCP1252:

MCP1252-33X50I/MS: Low-Noise, Positive-Regulated Charge Pump, Fixed Output a)

b) MCP1252-ADJI/MS:

Low-Noise, Positive-Regulated Charge Pump, Adjustable Output

MCP1252T-33X50I/MS: Tape and Reel, Low-Noise, Positive-Regulated Charge c)

Pump, Fixed Output

Examples for MCP1253:

MCP1253-33X50I/MS: Low-Noise, Positive-Regulated Charge Pump, Fixed Output a)

MCP1253-ADJI/MS: b)

Low-Noise, Positive-Regulated Charge Pump, Adjustable Output

c) MCP1253T-ADJI/MS: Tape and Reel, Low-Noise, Positive-Regulated Charge Pump, Adjustable Output

MCP1253T-ADJI/MSVAO: Tape and Reel, Low-Noise, Positive-Regulated Charge d)

Pump, Adjustable Output; Automotive qualified

MCP1253T-33X50I/MSVAO: Tape and Reel, Low-Noise, Positive-

Regulated Charge Pump, Fixed Output, Industrial, Automotive qualified

Note 1:

Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

N	IC	P1	25	2	13
---	----	-----------	----	---	----

NOTES:

Note the following details of the code protection feature on Microchip products:

- Microchip products meet the specifications contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is secure when used in the intended manner, within operating specifications, and under normal conditions.
- Microchip values and aggressively protects its intellectual property rights. Attempts to breach the code protection features of Microchip product is strictly prohibited and may violate the Digital Millennium Copyright Act.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of its code. Code protection does not
 mean that we are guaranteeing the product is "unbreakable" Code protection is constantly evolving. Microchip is committed to
 continuously improving the code protection features of our products.

This publication and the information herein may be used only with Microchip products, including to design, test, and integrate Microchip products with your application. Use of this information in any other manner violates these terms. Information regarding device applications is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. Contact your local Microchip sales office for additional support or, obtain additional support at https://www.microchip.com/en-us/support/design-help/client-support-services.

THIS INFORMATION IS PROVIDED BY MICROCHIP "AS IS". MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION INCLUDING BUT NOT LIMITED TO ANY IMPLIED WARRANTIES OF NON-INFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE, OR WARRANTIES RELATED TO ITS CONDITION, QUALITY, OR PERFORMANCE.

IN NO EVENT WILL MICROCHIP BE LIABLE FOR ANY INDIRECT, SPECIAL, PUNITIVE, INCIDENTAL, OR CONSEQUENTIAL LOSS, DAMAGE, COST, OR EXPENSE OF ANY KIND WHATSOEVER RELATED TO THE INFORMATION OR ITS USE, HOWEVER CAUSED, EVEN IF MICROCHIP HAS BEEN ADVISED OF THE POSSIBILITY OR THE DAMAGES ARE FORESEEABLE. TO THE FULLEST EXTENT ALLOWED BY LAW, MICROCHIP'S TOTAL LIABILITY ON ALL CLAIMS IN ANY WAY RELATED TO THE INFORMATION OR ITS USE WILL NOT EXCEED THE AMOUNT OF FEES, IF ANY, THAT YOU HAVE PAID DIRECTLY TO MICROCHIP FOR THE INFORMATION.

Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

For information regarding Microchip's Quality Management Systems, please visit www.microchip.com/quality.

Trademarks

The Microchip name and logo, the Microchip logo, Adaptec, AVR, AVR logo, AVR Freaks, BesTime, BitCloud, CryptoMemory, CryptoRF, dsPIC, flexPWR, HELDO, IGLOO, JukeBlox, KeeLoq, Kleer, LANCheck, LinkMD, maXStylus, maXTouch, MediaLB, megaAVR, Microsemi, Microsemi logo, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, PolarFire, Prochip Designer, QTouch, SAM-BA, SenGenuity, SpyNIC, SST, SST Logo, SuperFlash, Symmetricom, SyncServer, Tachyon, TimeSource, tinyAVR, UNI/O, Vectron, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AgileSwitch, APT, ClockWorks, The Embedded Control Solutions Company, EtherSynch, Flashtec, Hyper Speed Control, HyperLight Load, Libero, motorBench, mTouch, Powermite 3, Precision Edge, ProASIC, ProASIC Plus, ProASIC Plus logo, Quiet- Wire, SmartFusion, SyncWorld, Temux, TimeCesium, TimeHub, TimePictra, TimeProvider, TrueTime, and ZL are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, Augmented Switching, BlueSky, BodyCom, Clockstudio, CodeGuard, CryptoAuthentication, CryptoAutomotive, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, Espresso T1S, EtherGREEN, GridTime, IdealBridge, In-Circuit Serial Programming, ICSP, INICnet, Intelligent Paralleling, IntelliMOS, Inter-Chip Connectivity, JitterBlocker, Knob-on-Display, KoD, maxCrypto, maxView, memBrain, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, PowerSmart, PureSilicon, QMatrix, REAL ICE, Ripple Blocker, RTAX, RTG4, SAM-ICE, Serial Quad I/O, simpleMAP, SimpliPHY, SmartBuffer, SmartHLS, SMART-I.S., storClad, SQI, SuperSwitcher, SuperSwitcher II, Switchtec, SynchroPHY, Total Endurance, Trusted Time, TSHARC, USBCheck, VariSense, VectorBlox, VeriPHY, ViewSpan, WiperLock, XpressConnect, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

The Adaptec logo, Frequency on Demand, Silicon Storage Technology, and Symmcom are registered trademarks of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2002-2023, Microchip Technology Incorporated and its subsidiaries.

All Rights Reserved.

ISBN: 978-1-6683-3047-0



Worldwide Sales and Service

AMERICAS

Corporate Office 2355 West Chandler Blvd.

Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support:

http://www.microchip.com/

support Web Address:

www.microchip.com

Atlanta Duluth, GA

Tel: 678-957-9614 Fax: 678-957-1455

Austin, TX Tel: 512-257-3370

Boston

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL

Tel: 630-285-0071 Fax: 630-285-0075

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Novi. MI

Tel: 248-848-4000

Houston, TX

Tel: 281-894-5983 Indianapolis

Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453 Tel: 317-536-2380

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608 Tel: 951-273-7800

Raleigh, NC Tel: 919-844-7510

New York, NY Tel: 631-435-6000

San Jose, CA Tel: 408-735-9110 Tel: 408-436-4270

Canada - Toronto Tel: 905-695-1980 Fax: 905-695-2078

ASIA/PACIFIC

Australia - Sydney Tel: 61-2-9868-6733

China - Beijing Tel: 86-10-8569-7000

China - Chengdu Tel: 86-28-8665-5511

China - Chongqing Tel: 86-23-8980-9588

China - Dongguan Tel: 86-769-8702-9880

China - Guangzhou Tel: 86-20-8755-8029

China - Hangzhou Tel: 86-571-8792-8115

China - Hong Kong SAR Tel: 852-2943-5100

China - Nanjing Tel: 86-25-8473-2460

China - Qingdao Tel: 86-532-8502-7355

China - Shanghai Tel: 86-21-3326-8000

China - Shenyang Tel: 86-24-2334-2829

China - Shenzhen Tel: 86-755-8864-2200

China - Suzhou Tel: 86-186-6233-1526

China - Wuhan Tel: 86-27-5980-5300

China - Xian Tel: 86-29-8833-7252

China - Xiamen
Tel: 86-592-2388138

China - Zhuhai Tel: 86-756-3210040

ASIA/PACIFIC

India - Bangalore Tel: 91-80-3090-4444

India - New Delhi Tel: 91-11-4160-8631

India - Pune Tel: 91-20-4121-0141

Japan - Osaka

Tel: 81-6-6152-7160 Japan - Tokyo

Tel: 81-3-6880- 3770

Korea - Daegu Tel: 82-53-744-4301

Korea - Seoul Tel: 82-2-554-7200

Malaysia - Kuala Lumpur Tel: 60-3-7651-7906

Malaysia - Penang Tel: 60-4-227-8870

Philippines - Manila Tel: 63-2-634-9065

Singapore Tel: 65-6334-8870

Taiwan - Hsin Chu

Tel: 886-3-577-8366 **Taiwan - Kaohsiung**

Tel: 886-7-213-7830

Taiwan - Taipei Tel: 886-2-2508-8600

Thailand - Bangkok Tel: 66-2-694-1351

Vietnam - Ho Chi Minh Tel: 84-28-5448-2100

EUROPE

Austria - Wels

Tel: 43-7242-2244-39 Fax: 43-7242-2244-393

Denmark - Copenhagen Tel: 45-4485-5910 Fax: 45-4485-2829

Finland - Espoo Tel: 358-9-4520-820

France - Paris Tel: 33-1-69-53-63-20

Fax: 33-1-69-30-90-79 **Germany - Garching**

Tel: 49-8931-9700 **Germany - Haan** Tel: 49-2129-3766400

Germany - Heilbronn Tel: 49-7131-72400

Germany - Karlsruhe Tel: 49-721-625370

Germany - Munich Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Germany - Rosenheim Tel: 49-8031-354-560

Israel - Ra'anana Tel: 972-9-744-7705

Italy - Milan Tel: 39-0331-742611 Fax: 39-0331-466781

Italy - Padova Tel: 39-049-7625286

Netherlands - Drunen Tel: 31-416-690399 Fax: 31-416-690340

Norway - Trondheim Tel: 47-7288-4388

Poland - Warsaw Tel: 48-22-3325737

Romania - Bucharest Tel: 40-21-407-87-50

Spain - Madrid Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

Sweden - Gothenberg Tel: 46-31-704-60-40

Sweden - Stockholm Tel: 46-8-5090-4654

UK - Wokingham Tel: 44-118-921-5800 Fax: 44-118-921-5820